

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		S82 and (Co or cobalt near10 .percent.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:33
		S82 and (Co or cobalt near10 %)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:33
		hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near "0."	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:08
		S56 and "0." {2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:50
		S56 and "0."{2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:50
		S49 and "0."{2d} and (ni or nickel) and (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:50
		S49 and (ni or nickel) and (co or cobalt) and "0."{2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:49

		S49 and (ni or nickel) and (co or cobalt) and "0."{2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:49
		S49 and (ni or nickel) and (co or cobalt) and "0."{2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:48
		S49 and (ni or nickel) and (co or cobalt) and "0.0"{2d}	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:48
		S40 and (ni or nickel) and (co or cobalt) .u.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:42
S1	0	2004/0023487	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:08
S2	2	"20040023487"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:08
S3	2	"2000164746"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:09
S4	0	"11654699"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:09

S5	3	"2003209197"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:09
S6	2	"2000106408"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 14:09
S7	622	257/710.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:16
S8	7056	257/704,710, E23.128, E23.18-E23.193.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:25
S9	8649	438/124-127,106.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:25
S10	15057	S8 or S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:25
S11	1874	S10 and hermetic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:25
S12	2975	S10 and hermetic\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:25

S13	484	S12 and (memory or storage)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:26
S14	0	S12 and difus\$3 accelerator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:26
S15	1	S12 and diffus\$3 accelerator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:26
S16	10	S12 and diffus\$3 near10 accelerat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:27
S17	52	S12 and diffus\$3 near10 (accelerat\$3 or speed or increas\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:29
S18	158	S12 and solder layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:30
S19	1750	S12 and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:30
S20	755	S19 and (sn or tin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:30

S21	365	S20 and (cobalt or co)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:31
S22	30	S21 and (Fe\$1Ni\$1Co)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:32
S23	141	S21 and (Fe\$1Ni\$1Co or KOVAR)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:32
S24	141	S21 and (Fe\$1Ni\$1Co or Cobalt\$1nickel\$1iron or KOVAR)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:33
S25	10	S21 and ((Fe\$1Ni\$1Co or Cobalt\$1nickel\$1iron or KOVAR) near5 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:35
S26	10	S21 and (Fe\$1Ni\$1Co or Cobalt\$1nickel\$1iron or KOVAR) and ((Fe\$1Ni \$1Co or Cobalt\$1nickel \$1iron or KOVAR) near5 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:36
S27	11	hermetic\$4 and package and seal\$3 and cap and solder and (Fe\$1Ni\$1Co or Cobalt\$1nickel\$1iron or KOVAR) and ((Fe\$1Ni \$1Co or Cobalt\$1nickel \$1iron or KOVAR) near5 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:40
S28	726	hermetic\$4 and package and seal\$3 and cap and solder and (second layer near ni or nickel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:43

S29	4	hermetic\$4 and package and seal\$3 and cap and solder and (second layer near (ni or nickel))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:43
S30	11	hermetic\$4 and package and seal\$3 and cap and solder and (second layer near10 (ni or nickel))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 15:43
S31	2905	hermetic\$4 and seal\$3 and cap and semiconductor and package	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 16:26
S32	150	S31 and solder layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 16:26
S33	0	S32 and (ni or nickel) and (ni\$1co or nickel\$1cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 16:28
S34	110	S32 and (ni or nickel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 16:28
S35	60	S32 and (ni or nickel) and (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/27 16:29
S36	28	("2594933" "2643221" "3304362" "3946190" "4305997" "4320169" "4356047" "4411965" "4503131" "4601958" "4620661" "4626479" "4640438" "4649229" "4666796" "4737418"). PN. OR ("4842961"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/27 16:44

S37	2	"4666796".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:37
S38	35	("2428033" "3199003" "3219748" "3221219" "3362851" "3364064" "3823468" "3874549" "3946190" "4243729" "4284481" "4411965" "4486622").PN. OR ("4666796").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/28 10:38
S39	2909	hermetic\$4 and seal\$3 and cap and semiconductor and package	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:42
S40	150	S39 and solder layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:42
S41	0	S40 and (ni or nickel) and (co or cobalt) ".micro"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:42
S42	0	S40 and (ni or nickel) and (co or cobalt) "u."	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:42
S43	7060	257/704,710,E23.128, E23.18-E23.193.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:43
S44	8654	438/124-127,106.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:43

S45	15065	S43 or S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:43
S46	630	S45 and hermetic\$4 and seal\$3 and cap and semiconductor and package	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:43
S47	271	S46 and (ni or nickel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:44
S48	144	S46 and (ni or nickel) and (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:44
S49	1008	S45 and hermetic\$4 and seal\$3 and cap	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:45
S50	210	S49 and (ni or nickel) and (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:45
S51	36	S49 and ((ni or nickel) and (co or cobalt) near10 layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:45
S52	0	S49 and (ni or nickel) and (co or cobalt) and "0.0{d}{d}" ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:46

S53	0	S49 and (ni or nickel) and (co or cobalt) and "0.0 {d}" ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:46
S54	0	S49 and (ni or nickel) and (co or cobalt) and "0.0 {d}"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:47
S55	0	S49 and (ni or nickel) and (co or cobalt) and "{d}. {2d}"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:47
S56	210	S49 and (ni or nickel) and (co or cobalt)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:50
S57	77	S56 and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 10:50
S58	0	("2008/0271908").URPN.	USPAT	ADJ	ON	2009/05/28 10:58
S59	9	hermetic\$4 and seal\$3 and cap and semiconductor and package and thin\$1plat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:07
S60	0	hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near "0.")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:08
S61	0	hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near10 "0.0")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:08

S62	0	hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near10 "0.{ d} ")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:08
S63	89	hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near10 "0.{ d} ")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:08
S64	6	hermetic\$4 and seal\$3 and cap and semiconductor and package and (plat\$3 near10 "0.0"{ d})	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:09
S65	192	hermetic\$4 and seal\$3 and cap and package and (plat\$3 same "0.0"{ d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:12
S66	192	hermetic\$4 and seal\$3 and cap and package and (plat\$3 same "0.0"{ d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:12
S67	28	S45 and cap and package and (plat\$3 same "0.0"{ d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:13
S68	5	S45 and cap and package and (plat\$3 same ((Ni or nickel) near10 "0.0"{ d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:14
S69	5	("20030080411" "5578869" "6229404" "6489558").PN. OR ("7173331").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/28 11:16
S70	2042	257/704,710.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:20

S71	0	S70 and cap.ti. and (ni or nickel) near "0.0"{d} and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:21
S72	1	S70 and cap.ti. and ((ni or nickel) near10 "0.0"{d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:21
S73	2	S70 and cap and ((ni or nickel) near10 "0.0"{d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:22
S74	4	S70 and plat\$3 and ((ni or nickel) near10 "0.0"{d}) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:23
S75	4	S70 and (plat\$3 same ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:23
S76	762	(plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:26
S77	0	(flash\$1plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:26
S78	762	(plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:26

S79	253	package and (plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:26
S80	65	cap and (plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:26
S81	9	cap same (plat\$3 near5 ((ni or nickel) near10 "0.0"{d})) and ".mu.m"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:27
S82	27	(US-20040023487-\$ or US-20040183172-\$ or US-20040104460-\$ or US-20030104651-\$ or US-20050023661-\$ or US-20040036156-\$).did. or (US-4769345-\$ or US-3874549-\$ or US-4243729-\$ or US-4291815-\$ or US-4331258-\$ or US-4750665-\$ or US-4746583-\$ or US-4842961-\$ or US-5095359-\$ or US-6872470-\$ or US-6390353-\$ or US-4737418-\$ or US-4666796-\$ or US-4601958-\$ or US-4356047-\$ or US-5898218-\$ or US-6100108-\$ or US-4236296-\$).did. or (JP-2000164746-\$ or JP-2003209197-\$ or JP-2000106408-\$).did.	US-PGPUB; USPAT; JPO	ADJ	ON	2009/05/28 11:33
S83	15	S82 and (Co or cobalt near10 "%")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:34
S84	1	S82 and ((Co or cobalt) near10 "%")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:35

S85	0	hermetic\$4 and package and seal\$3 and cap and solder and (first layer near (co or cobalt))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:50
S86	12	hermetic\$4 and package and seal\$3 and cap and solder and (layer near (co or cobalt))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 11:50
S87	50	hermetic\$4 and package and seal\$3 and (cap or lid or cover) and solder and (layer near (co or cobalt))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 13:41
S88	0	hermetic\$4 and package and seal\$3 and (cap or lid or cover) and solder and (layer near (co or cobalt) near5 "5")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 13:41
S89	0	hermetic\$4 and package and seal\$3 and (cap or lid or cover) and solder and (layer near (co or cobalt) near5 "%")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 13:41
S90	27	(US-20040023487-\$ or US-20040183172-\$ or US-20040104460-\$ or US-20030104651-\$ or US-20050023661-\$ or US-20040036156-\$).did. or (US-4769345-\$ or US-3874549-\$ or US-4243729-\$ or US-4291815-\$ or US-4331258-\$ or US-4750665-\$ or US-4746583-\$ or US-4842961-\$ or US-5095359-\$ or US-6872470-\$ or US-6390353-\$ or US-4737418-\$ or US-46666796-\$ or US-4601958-\$ or US-4356047-\$ or US-5898218-\$ or US-6100108-\$ or US-4236296-\$).did. or (JP-2000164746-\$ or JP-2003209197-\$ or JP-2000106408-\$).did.	US-PGPUB; USPAT; JPO	ADJ	ON	2009/05/28 14:16
S91	7	S90 and solder layer	US-PGPUB; USPAT; JPO	ADJ	ON	2009/05/28 14:16

S92	5	"2005123297"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/28 16:47
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